**Product / Process Change Notice**

**Parts Affected:**

TVS diodes manufactured in the SMC case as shown below

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| SMC TVS diodes |
| 1.5SMC6.8A-1.5SMC220A1.5SMC6.8CA-1.5SMC220CA |

**Extent of Change:**

Additional wafer fab site

**Reason for Change:**

As part of Central Semiconductor’s supply chain risk mitigation initiative, in an effort to ensure an undisrupted supply of product, an additional wafer fabrication site is being added for the referenced product families. Product specifications, quality and reliability are not impacted by this addition.

**Effect of Change:**

This addition does not affect the fit, form or function of devices

**Qualification:**

|  |  |  |
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| **Test** | **Condition** | **Failure rate** |
| **Resistance to Solder Shock**  | T =260°C ±5°CDwell time = 10 sec.**JESD22-B106** | 0/77 |
| **High Temperature Storage Life/ bake test.** |  150°C (-0/+10)°C, 1000 hours.**JESD22-A103** | 0/77 |
| **Temperature Cycling** | T= -65°C to +150°C1000 cycles. Dwell time = 15 min.**JESD22-A104** | 0/77 |
| **High Temperature Reverse Bias (HTRB)** | T=125°C, t=1000 hours, VR=VZ**JESD22-A108** | 0/77 |
| **Highly Accelerated Temperature and Humidity Stress Test (HAST)** | T = 130°C, RH = 85%, P = 33.3 psia, and t = 96 hours.Bias conditions per device specification sheet.**JESD22-A110** | 0/77 |
| **Accelerated Moisture Resistance Unbiased Autoclave** | Temperature = 121°C ± 2°C; relative humidity = 100%; vapor pressure = 29.7 psia (15psig). t=96 hours**JESD22-A102** | 0/77 |

**Effective Date of Change:**

Existing inventory will be shipped until depleted.

**Sample Availability:**

Please contact your salesperson or manufacturer’s representative for samples.

As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor’s Product/Process Change Notification (PCN).

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| Company Name: |  |
| Address: |  |
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|  |
| Printed Name: |  |
| Title: |  |
| Signature: |  |
| Date: |  |